

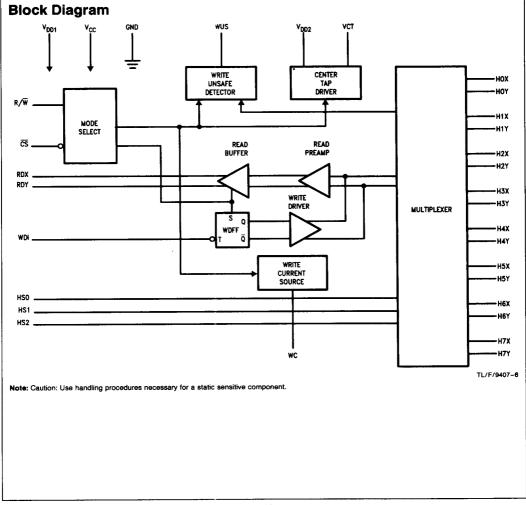
DP501X/DP501XR/ μ A501X/ μ A501XR Series 6 or 8 Channel Read/Write Circuit

General Description

The μ A501X/ μ A501XR devices are bipolar monolithic integrated circuits designed for use with center-tapped ferrite recording heads. They provide a low noise read path, write current control, and data protection circuitry for eight channels. The μ A501X/ μ A501XR requires +5.0V and +12V power supplies and is available in a variety of packages. The μ A501XR differs from the μ A501X by having internal damping resistors.

Features

- +5.0V, +12V power supplies
- Single- or multi-platter Winchester drives
- Designed for center-tapped ferrite heads
- Programmable write current source
- Easily multiplexed for larger systems
- Includes write unsafe detection
- TTL compatible control signals



Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Storage	T	emper	ature	R	ange

Ceramic DIP and Flatpak -65°C to +175°C Molded DIP and PLCC -65°C to +150°C 0°C to +70°C

Operating Temperature Range

Lead Temperature

Ceramic DIP and Flatpak (Soldering, 60 seconds) Molded DIP and PLCC (Soldering, 10 seconds)

Internal Power Dissipation (Notes 2 & 3)

28L-Ceramic DIP 2.50W 28L-Plastic DIP 1.92W 32L-Brazed Flatpak 1.88W 40L-Ceramic DIP 2.65W 40L-Plastic DIP 2.5W 28L-Plastic LCC 1.39W 44L-Plastic LCC 1.92W

DC Supply Voltage

V_{DD1} and V_{DD2} -0.3V to +14V V_{CC} -0.3V to +6.0VDigital Input Voltage Range -0.3V to V_{CC} + 0.3V

Head Port Voltage Range -0.3V to $V_{DD} + 0.3V$

-0.3V to +14VWUS Port Voltage Range 1 Write Current 60 mA

Output Current

RDX and RDY -- 10 mA VCT -60 mA WUS + 12 mA

Note 1: All voltages referenced to GND.

Note 2: T_{J MAX} = 150°C for the Plastic, and 175°C for the Ceramic.

Note 3: Ratings apply to ambient temperature at 25°C. Above this temperature, derate the 28L-Ceramic DIP at 16.7 mW/°C, the 28L-Plastic DIP at 15.3 mW/°C, the 32L-Brazed Flatpak at 12.5 mW/°C, the 40L-Ceramic DIP at 20.1 mW/°C, the 40L-Plastic DIP at 20 mW/°C, the 28L-Plastic LCC at 11.2 mW/°C, and the 44L-Plastic LCC at 15.3 mW/°C.

Recommended Operating Conditions

DC Supply Voltage

12V ± 10% V_{DD1} V_{CC} 5V ± 10% Head Inductance (Lh) $5.0 \mu H$ to $15 \mu H$

Damping Resistor (External)

RD (DP501X Only) 500 Ω to 2000 Ω **RCT Resistor** 90Ω ±5.0% (1/2W)

Write Current (I_W) 25 mA to 50 mA

DC Electrical Characteristics

 $V_{DD1} = 12V \pm 10\%$, $V_{CC} = 5.0V \pm 10\%$, $0^{\circ}C \le T_A \le +70^{\circ}C$, unless otherwise specified

300°C

265°C

Symbol	Parameter		Conditions		Min	Max	Units
Icc	ICC Supply Current		Read/Idle Mode			25	mA.
			Write Mode			25	,,,,
IDD	Supply Current		Idle Mode			20	
			Read Mode			40	mA
			Write Mode			20 + I _W	
PC	Power Consumption		25°C ≤ T _J ≤ 135°C	Idle Mode		400	
				Read Mode		650	
				Write Mode, $I_W = 50 \text{ mA},$ $RCT = 90\Omega$		880	mW
				Write Mode, $I_W = 50 \text{ mA},$ RCT = 0Ω		1060	
VIL	Digital Input Voltage LOW				-0.3	0.8	٧
V _{IH}	Inputs:	Input Voltage HIGH			2.0	V _{CC} + 0.3	٧
l _{IL}		Input Current LOW	$V_{IL} = 0.8V$		0.4		mA
hн		Input Current HIGH	$V_{IH} = 2.0V$			100	μΑ
V _{OL}	WUS Output		I _{OL} = 8.0 mA			0.5	٧
Юн			V _{OH} = 5.0V			100	μΑ
V _{CT}	Center Ta	ιρ Voltage	Read Mode		4	.0 (typ)	٧
			Write Mode		6	.0 (typ)	V

Write Characteristics $V_{DD1}=12V\pm10\%, V_{CC}=5.0V\pm10\%, 0^{\circ}C \leq T_{A} \leq +70^{\circ}C, I_{W}=45$ mA, Lh = 10 μ H, Rd = 750Ω (DP501X only), f(Data) = 5.0 MHz, CL (RDX, RDY) \leq 20 pF, unless otherwise specified

Parameter	Conditions	Min	Max	Units
Write Current Range		10	50	mA
Write Current Constant "K"		129	151	V
Differential Head Voltage Swing		7.5		V (pk)
Unselected Head Transient Current	5.0 μH ≤ Lh ≤ 9.5 μH		2.0	mA (pk)
Differential Output Capacitance			15	pF
Differential Output Resistance	Without Internal Resistors	10k		Ω
	With Internal Resistors	560	940	
WDI Transition Frequency	WUS = LOW	250		kHz
Head Current Gain to $I_{WC}\left(\frac{I_{W}}{I_{WC}}\right)$		20	(typ)	mA/mA
Unselected Head Leakage	Sum of X and Y Side Current		85	μА

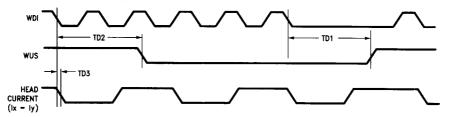
Read Characteristics $V_{DD1}=12V\pm10\%,\ V_{CC}=5.0V\pm10\%,\ I_W=45$ mA, CL (RDX, RDY) ≤ 20 pF, (V_{IN} is referenced to V_{CT}), $0^{\circ}C\leq T_A\leq +70^{\circ}C$, Lh = 10 μ H, Rd = 750 Ω , f(Data) = 5.0 MHz unless otherwise specified

Characteristic	Condition		Min	Max	Unit
Differential Voltage Gain	$V_{IN} = 1.0 \text{ mV}_{PP} \text{ at } 300 \text{ kHz}$ RL (RDX), RL (RDY) = 1.0 k Ω (AC coupled)		80	120	V/V
Dynamic Range	Input Voltage, V_i , where $V_{iN} = V_i + 0.5 \text{ mV}_i$	-3.0	3.0	m∨	
Bandwidth (-3 dB)	$ Zs < 5.0\Omega$, $V_{IN} =$	1.0 mV _{PP}	30		MHz
Input Noise Voltage	BW = 15 MHz, Lh :	= 0, Rh = 0		1.5	nV/√Hz
Differential Input Capacitance	f = 5.0 MHz			23	pF
Differential Input Resistance	f = 5.0 MHz,	Without Internal Resistors	2k		Ω
	V _{IN} ≤ 6 mV _{PP}	With Internal Resistors	530	790	
Input Bias Current (per Side)				100	μΑ
Common Mode Rejection Ratio	V _{CM} = V _{CT} + 100 mV _{PP} at 5.0 MHz		50		dB
Power Supply Rejection Ratio	100 mV _{PP} at 5.0 MHz on V _{DD1} , V _{DD2} , or V _{CC}		45		dB
Channel Separation	Unselected Channels: V _{IN} = 100 mV _{PP} at 5.0 MHz and Selected Channel: V _{IN} = 0 mV _{PP}		45		dB
Output Offset Voltage			-480	480	mV
Common Mode Output Voltage		Read Mode	5.0	7.0	V
		Write/Idle Mode	4.3 (typ)	•
Single Ended Output Resistance	f = 5.0 MHz			30	Ω
External Resistive Load (AC Coupled to Output)	Per Side to GND		100		Ω
Leakage Current (RDX, RDY)	5.0 < RDX, RDY < 8.0V Write or Idle Mode		-50	50	μΑ
Center Tap Output Impedance	0 ≤ f ≤ 5.0 MHz			150	Ω_
Output Current	AC Coupled Load RDX to RDY		2.0		mA

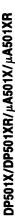
Switching Characteristics $V_{DD1}=12V\pm10\%, V_{CC}=5.0V\pm10\%, 0^{\circ}C \leq T_{A} \leq +70^{\circ}C, I_{W}=45 \text{ mA, Lh}=10 \ \mu\text{H, Rd}=750\Omega, f(Data)=5.0 \text{ MHz, unless otherwise specified}$

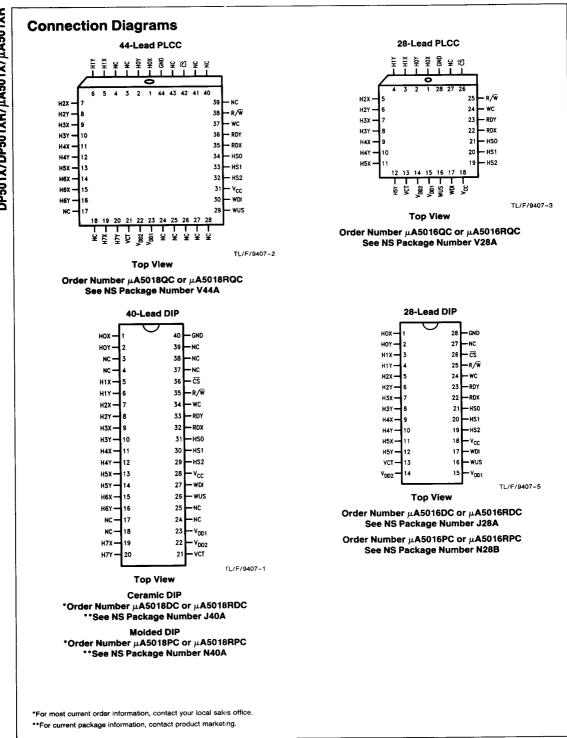
Symbol	Parameter	Conditions	Min	Max	Units
R/W to Write		Delay to 90% of Write Current		600	
	R/W to Read	Delay to 90% of 100 mV, 10 MHz Read Signal Envelope or to 90% Decay of Write Current		600	ns
CS	CS to Select	Delay to 90% of Write Current or to 90% of 100 mV, 10 MHz Read Signal Envelope		600	ns
CS to Unselect		Delay to 90% Decay of Write Current		600	1
HS0 HS1 HS2	to Any Head	Delay to 90% of 100 mV, 10 MHz Read Signal Envelope		600	ns
WUS Safe to Unsafe—TD1 Unsafe to Safe—TD2		I _W = 50 mA	1.6	8.0	
		I _W = 20 mA		1.0	μs
Head Propagation Delay—TD3 Current		$\label{eq:Lh} \begin{array}{l} \text{Lh} = 0 \mu \text{H, Rh} = 0 \Omega \\ \text{from 50\% Points} \end{array}$		30	
	Asymmetry	WDI has 50% Duty Cycle and 1 ns Rise/Fall Time		2	ns
	Rise/Fall Time	10%-90% Points		20	

Write Mode Timing Diagram

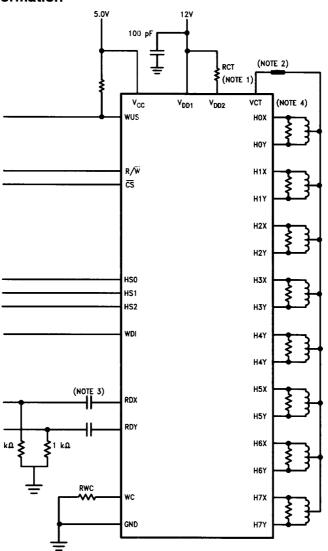


TL/F/9407-8





Application Information



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Note 1: An external ½W resistor, RCT, given by RCT = 90 (50/I_W)Ω, where I_W is in mA can be used to limit internal power dissipation. Otherwise connect V_{DD2} to V_{DD1}.

Note 2: A ferrite bead (Ferroxcube 5659065/4A6) can be used to suppress write current overshoot and ringing induced by flex cable parasitics.

Note 3: Limit DC current from RDX and RDY to 100 μA and load capacitance to 20 pF.

Note 4: Damping resistors required on DP501X only.

Pin Descriptions

TABLE I. Description of Lead Functions

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Name	Functions				
HS0-HS2	Head Select				
CS	Chip Select: a low level enables device.				
R/₩	Read/Write: a high level selects read mode.				
wus	Write Unsafe: a high level indicates an unsafe writing position.				
WDI	Write Data In: a negative transition toggles the direction of the head current.				
H0X-H7X H0Y-H7Y	X, Y Head Connections				
RDX, RDY	X,Y Read Data: differential read signal out.				
wc	Write Current: used to set the magnitude of the write current.				
VCT	Voltage Center Tap: voltage source for head center tap.				
V _{CC}	+5.0V				
V _{DD1}	+ 12V				
V _{DD2}	Positive power supply for the center tap voltage source.				
GND	Ground				

Circuit Operation

The μ A510X/ μ A501XR functions as a write driver or as a read amplifier for the selected head. Head selection and mode control are described in Tables II and III. Both R/W and $\overline{\text{CS}}$ have internal pull-up resistors to prevent an accidental write condition.

WRITE MODE

The Write mode configures the μ A510X/ μ A501XR as a current switch and activates the Write Unsafe Detector. Head current is toggled between the X- and Y-side of the recording head on the falling edges of WDI, Write Data Input. Note that a preceding read operation initializes the Write Data Flip-Flop, WDFF, to pass current through the X-side of the head. The magnitude of the write current, given by

 $I_W = K/Rwc$, where K = Write Current Constant is set by the external resistor, Rwc, connected from lead WC to GND.

TABLE II. Mode Select

CS	R/W	Mode
0	0	Write
0	1	Read
1	l x	ldle

TABLE III. Head Select

HS2	HS1	HS0	Head
0	0	0	0
0	o	1	1
0	1	0	2
0	1	1	3
1	0	0	4
1	0	1	5
1	1	0	6
1	1	1	7

- 0 = Low Level
- 1 = High Level

Any of the following conditions will be indicated as a high level on the Write Unsafe, WUS, open collector output.

- · Head open
- · Head center tap open
- · WDI frequency too low
- · Device in Read mode
- · Device not selected
- · No write current

After the fault condition is removed, two negative transitions on WDI are required to clear WUS.

READ MODE

In the Read mode the μ A510X/ μ A501XR is configured as a low noise differential amplifier, the write current source and the write unsafe detector are deactivated, and the write data flip-flop is set. The RDX and RDY outputs are driven by emitter followers and are in phase with the "X" and "Y" head ports. They should be AC coupled to the load.

Note that the internal write current source is deactivated for both the Read and the chip deselect mode. This eliminates the need for external gating of the write current source.